AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): An adhesive label comprising a circuit substrate, electronic components formed on at least one surface of said circuit substrate, and an adhesive layer on said electronic components, wherein said electronic components are sequentially laminated and said adhesive layer is in direct contact with said electronic components and is suitable for application to an article, when said adhesive label is applied to an article, said adhesive layer comes into direct contact with the surface of the article.

2. (original): The adhesive label according to claim 1, wherein said adhesive layer is a pressure sensitive adhesive layer.

3. (canceled).

4. (previously presented): The adhesive label according to claim 1 or 2, wherein an entire data carrier element for a contactless data carrier system containing said electronic components is formed on one side of said circuit substrate, and said adhesive layer is formed on said entire data carrier element.

5. (previously presented): The adhesive label according to claim 1 or 2, wherein a surface layer is provided on a circuit substrate surface that is on the reverse side to a surface carrying said electronic element.

6. (currently amended): The adhesive label according to claim 1, wherein said electronic components are separately formed on each surface of said circuit substrate and connected to each other by a through-hole to integrate both electronic components to form an entire data carrier element for a contactless data carrier system, said adhesive layer is formed on one of said separately formed electronic components, and a surface layer is formed directly on the other of said separately formed electronic components.

7. (previously presented): The adhesive label according to claim 4, wherein a surface layer is provided on a circuit substrate surface that is on the reverse side to a surface carrying said electronic element.